



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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# DB2130300L

Silicon epitaxial planar type

For rectification

■ Features

- Low forward voltage VF
- Small reverse leakage current
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: B4

■ Packaging

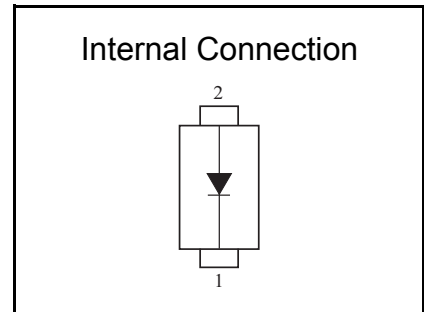
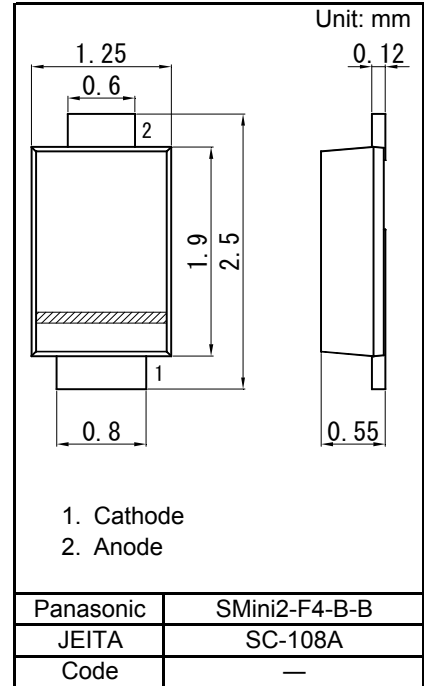
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	30	V
Maximum peak reverse voltage	VRM	30	V
Forward current (Average) <sup>*1</sup>	IF(AV)	1.0	A
Non-repetitive peak forward surge current <sup>*2</sup>	IFSM	20	A
Junction temperature	Tj	125	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +125	°C

Note: \*1 For embedded alumina substrate (substrate size:5 cm × 5 cm)

\*2 50 Hz sine wave 1 cycle (Non-repetitive peak current)





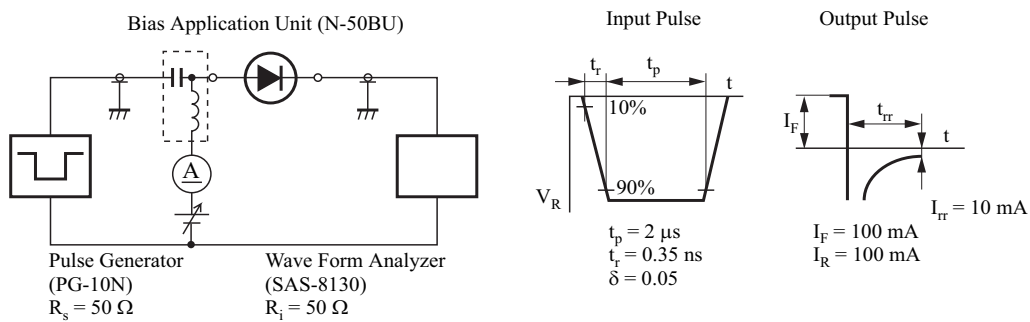
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF1	IF = 0.7 A			0.47	V
	VF2	IF = 1.0 A			0.49	
Reverse current	IR	VR = 30 V			40	μA
Terminal capacitance	Ct	VR = 10 V, f = 1 MHz		33		pF
Reverse recovery time *1	trr	IF = IR = 100 mA, Irr = 10 mA		11		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

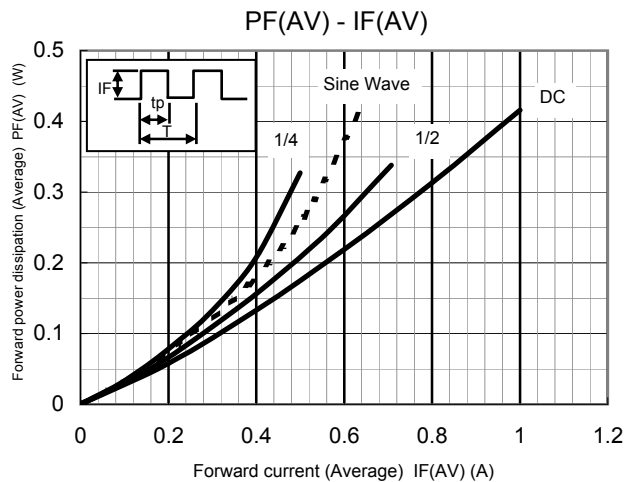
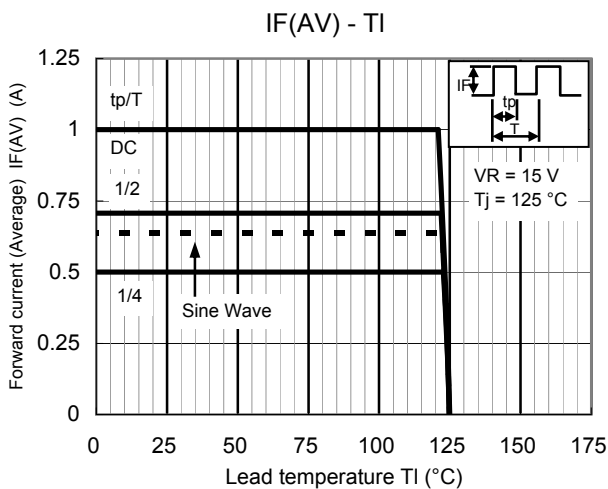
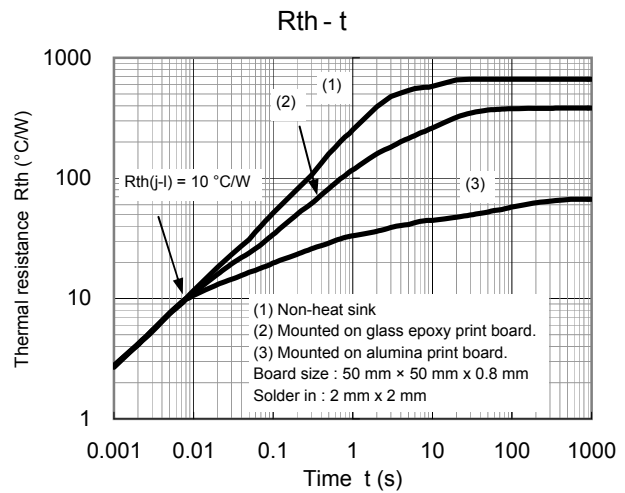
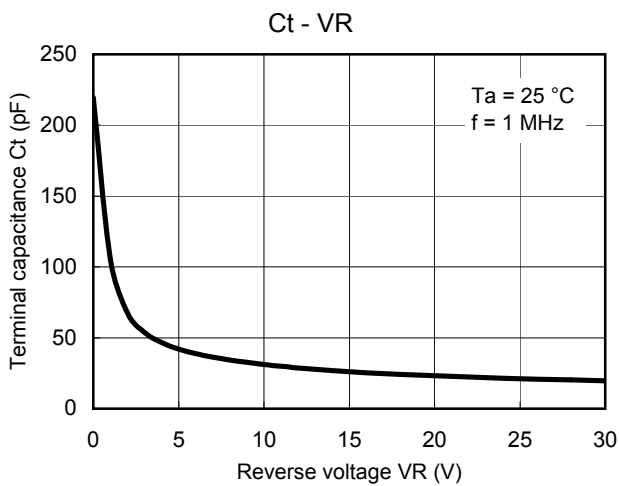
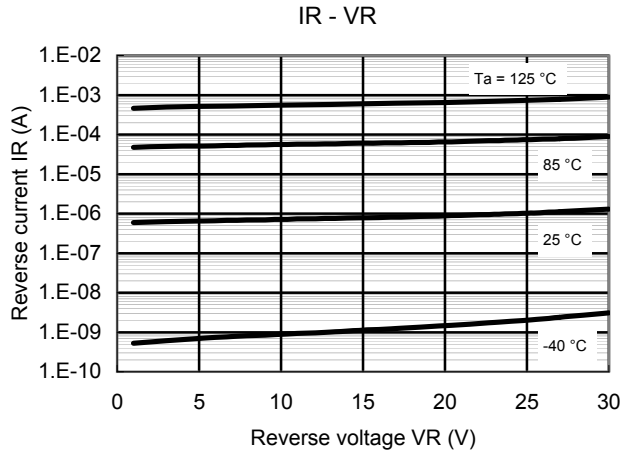
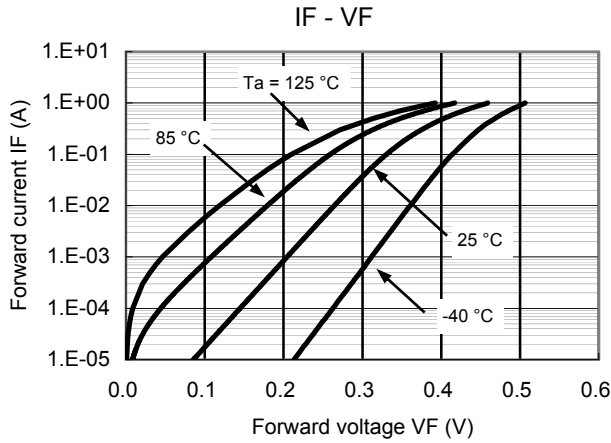
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*1 trr test circuit





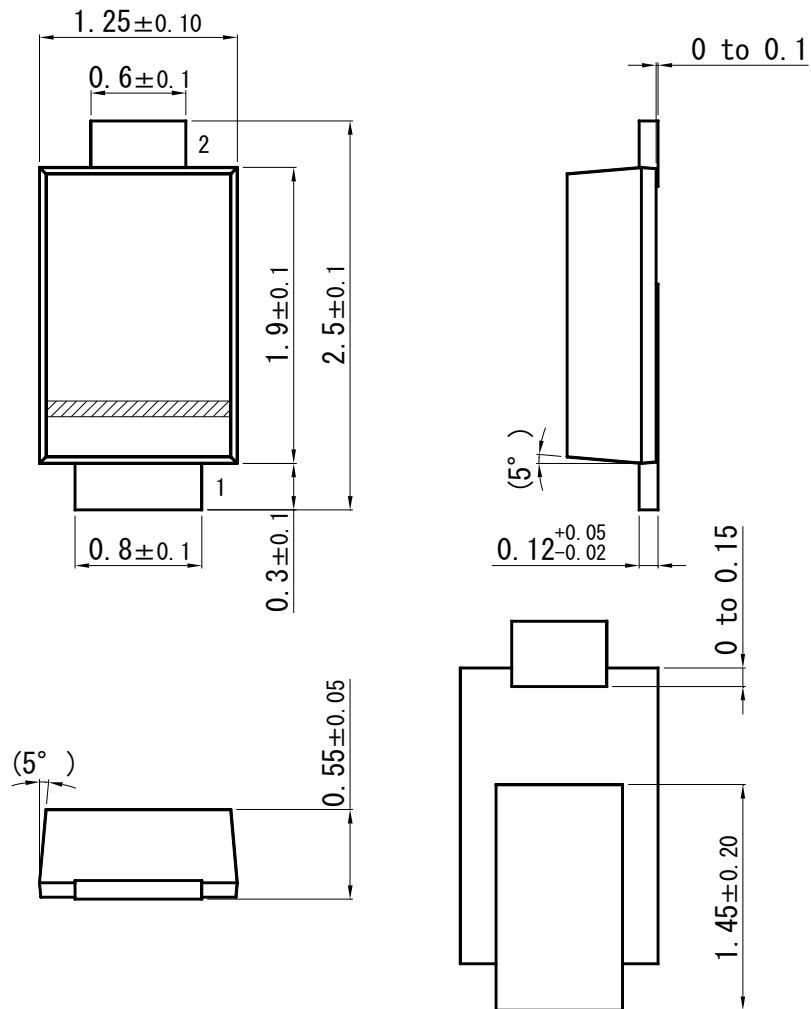
Technical Data ( reference )



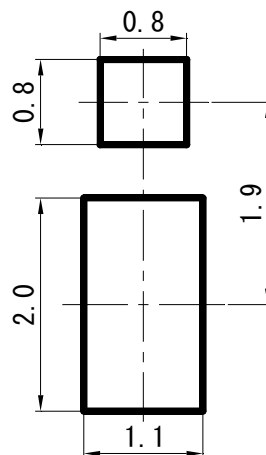


### SMini2-F4-B-B

Unit: mm



#### ■ Land Pattern (Reference) (Unit: mm)



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